



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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企业QQ二维码

## Features

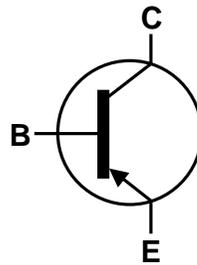
- $BV_{CEO} > -400V$
- $I_C = -500mA$  High Continuous Current
- $I_{CM} = -1A$  Peak Pulse Current
- Low Saturation Voltage  $V_{CE(sat)} < -250mV @ -50mA$
- $h_{FE} > 40$  Specified up to  $-200mA$  for High Current Gain Hold Up
- Complementary NPN Type: DIODES™ NK-FZT658

## Mechanical Data

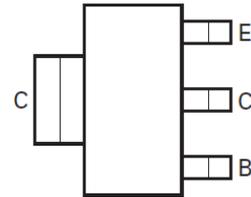
- Package: SOT223
- Package Material: Molded Plastic, "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 
- Weight: 0.112 grams (Approximate)



Top View



Device Symbol



Top View  
Pin-Out

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-400	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-400	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-0.5	A
Peak Pulse Current	I <sub>CM</sub>	-1	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

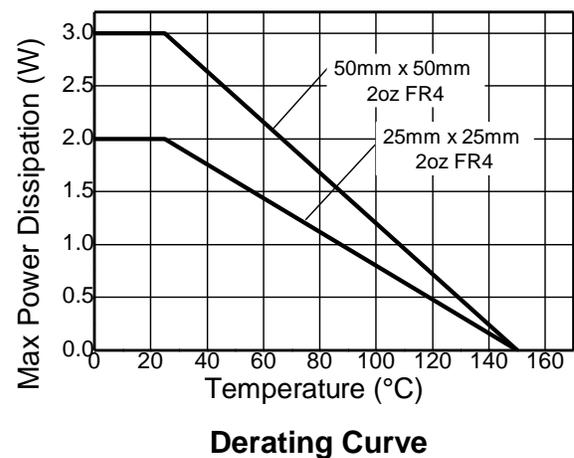
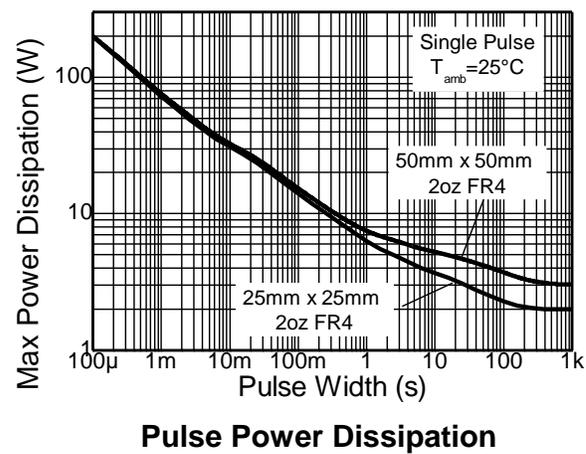
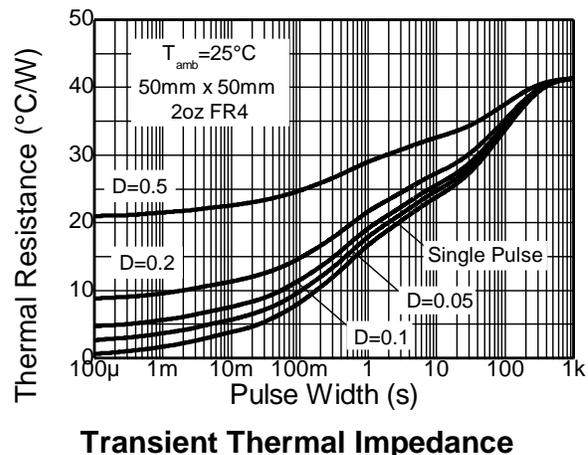
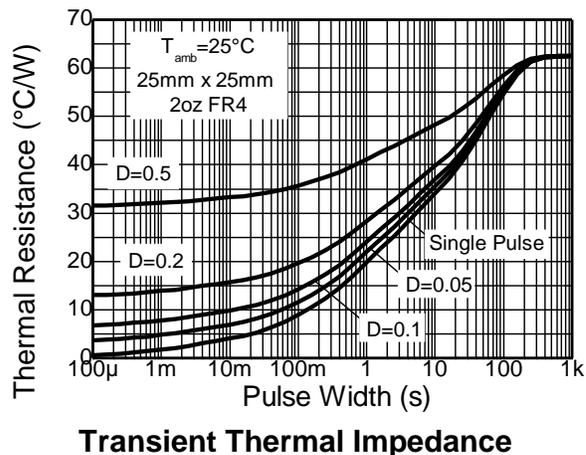
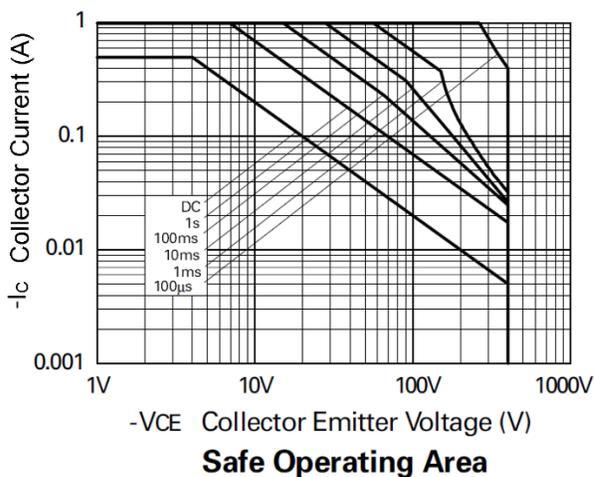
Characteristic	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	3.0	W
		(Note 5)	
		(Note 6)	
		(Note 7)	
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	1.6	°C/W
		(Note 8)	
		(Note 5)	
		(Note 6)	
Thermal Resistance Junction to Lead	R <sub>θJL</sub>	78.1	°C/W
		(Note 7)	
		(Note 8)	
Thermal Resistance Junction to Lead	(Note 9)	104	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**ESD Ratings** (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.
  7. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.
  8. Same as Note 5, except the device is mounted on minimum recommended pad layout.
  9. Thermal resistance from junction to solder-point (at the end of the collector lead).
  10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

## Thermal Characteristics and Derating Information

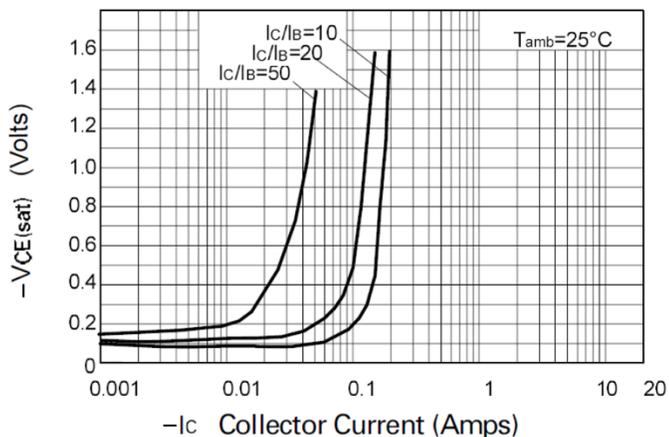


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

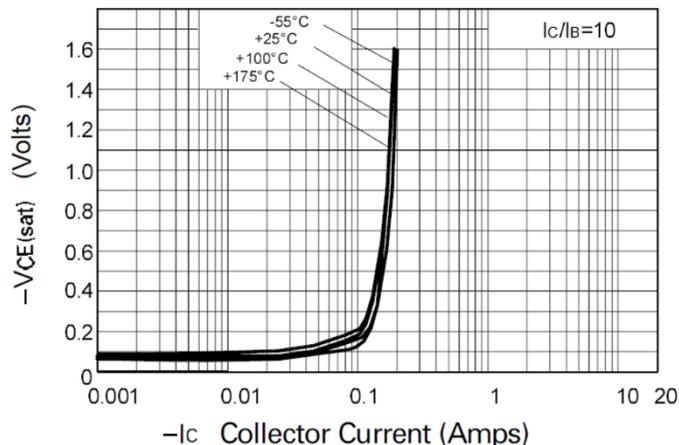
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	-400	–	–	V	$I_C = -100\mu A$
Collector-Emitter Breakdown Voltage (Note 11)	$BV_{CEO}$	-400	–	–	V	$I_C = -10mA$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	–	–	V	$I_E = -100\mu A$
Collector Cut-Off Current	$I_{CBO}$	–	–	-100	nA	$V_{CB} = -320V$
Collector Cut-Off Current	$I_{CES}$	–	–	-100	nA	$V_{CE} = -320V$
Emitter Cut-Off Current	$I_{EBO}$	–	–	-20	nA	$V_{EB} = -6V$
Collector-Emitter Saturation Voltage (Note 11)	$V_{CE(sat)}$	–	–	-0.30	V	$I_C = -20mA, I_B = -1mA$
				-0.25		$I_C = -50mA, I_B = -5mA$
				-0.50		$I_C = -100mA, I_B = -10mA$
Base-Emitter Saturation Voltage (Note 11)	$V_{BE(sat)}$	–	–	-0.9	V	$I_C = -100mA, I_B = -10mA$
Base-Emitter Turn-On Voltage (Note 11)	$V_{BE(on)}$	–	–	-1.0	V	$I_C = -100mA, V_{CE} = -5V$
DC Current Gain (Note 11)	$h_{FE}$	50	–	–	–	$I_C = -1mA, V_{CE} = -5V$
		50	–	–		$I_C = -100mA, V_{CE} = -5V$
		40	–	–		$I_C = -200mA, V_{CE} = -10V$
Current Gain-Bandwidth Product (Note 11)	$f_T$	50	–	–	MHz	$V_{CE} = -20V, I_C = -20mA, f = 20MHz$
Output Capacitance (Note 11)	$C_{obo}$	–	–	20	pF	$V_{CB} = -20V, f = 1MHz$
Switching Times	$t_{on}$	–	140	–	ns	$I_C = -100mA, V_{CC} = -100V, I_{B1} = -10mA, I_{B2} = 20mA$
	$t_{off}$	–	2,000	–		

 Note: 11. Measured under pulsed conditions. Pulse width  $\leq 300\mu s$ . Duty cycle  $\leq 2\%$ .

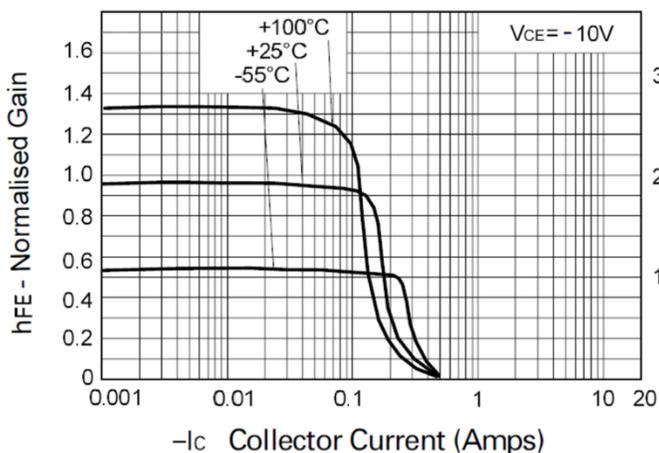
**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



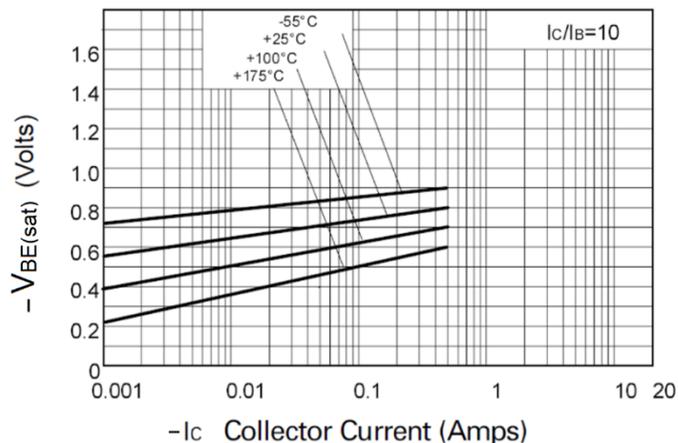
**VCE(sat) v IC**



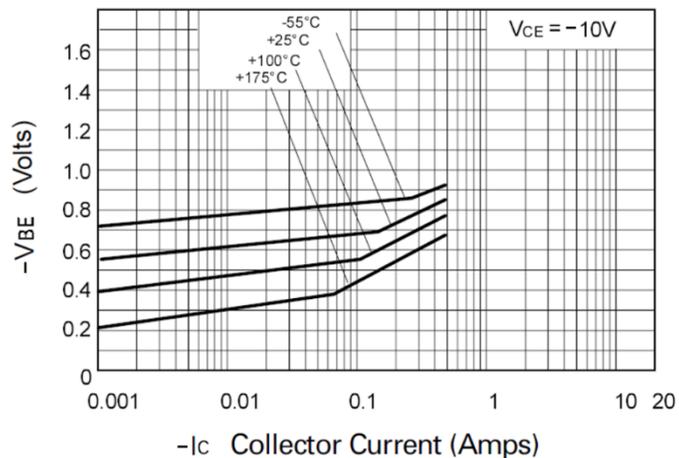
**VCE(sat) v IC**



**hFE v IC**



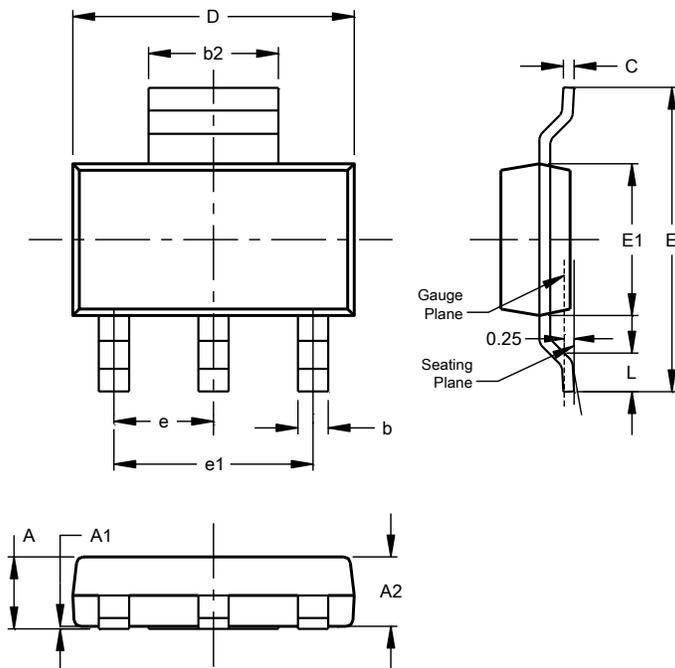
**VBE(sat) v IC**



**VBE(on) v IC**

### Package Outline Dimensions

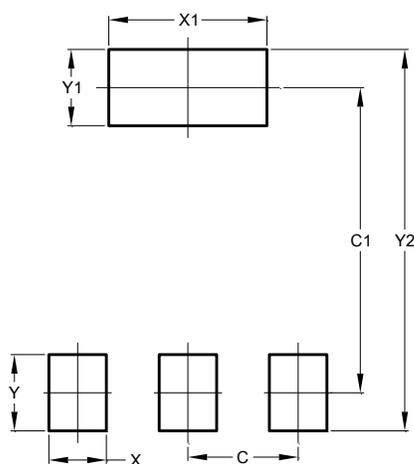
SOT223 (Type DN)



SOT223 (Type DN)			
Dim	Min	Max	Typ
A	--	1.70	--
A1	0.01	0.15	--
A2	1.50	1.68	1.60
b	0.60	0.80	0.70
b2	2.90	3.10	--
c	0.20	0.32	--
D	6.30	6.70	--
E	6.70	7.30	--
E1	3.30	3.70	--
e	--	--	2.30
e1	--	--	4.60
L	0.85	--	--
All Dimensions in mm			

### Suggested Pad Layout

SOT223 (Type DN)



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00